



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application No. :10/659,090 Confirmation No.:2724
Applicant :Christopher J. Nagel
Filed :September 10, 2003
TC/A.U. :1751
Examiner :Mark T. Kopec
Docket No. :2751.2001 US2
Title: COMPOSITION OF MATTER TAILORING: SYSTEM I

CERTIFICATE OF MAILING OR TRANSMISSION	
I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as First Class Mail in an envelope addressed to Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, or is being facsimile transmitted to the United States Patent and Trademark Office on:	
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DECLARATION UNDER 37 CFR 1.132

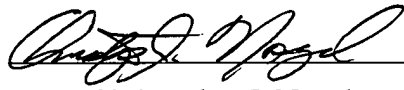
Sir:

I, Christopher J. Nagel, of 28 Highland Circle, Wayland MA 01778, am the sole inventor of the above identified application.

I am attaching an Excel spreadsheet of the data obtained from the following third party companies of the manufactured copper ingot (14-00-01) presented in the application: GDMS was obtained from SHIVA Technologies of Syracuse, New York; XRF was obtained from the University of Western Ontario, London, Ontario; PIXE was obtained from Elemental Analysis Incorporated, Lexington, Kentucky, and; GDOES was obtained from Twin Analytical of Independence, Ohio. The analysis is consistent with

the X-ray fluorescence (XRF) data presented in the application. The third party data confirmed that the manufactured copper ingot contains a different elemental signature that is different from the naturally occurring copper. The unique electronic characteristic of the manufactured copper is not a result from impurities but rather is an intrinsic property of the copper itself.

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.



Christopher J. Nagel

Compare at	date	11/13/2005	10/26/2005	10/24/2005	11/21/2005	1/8/2006	1/8/2006
20	analysis	GDMS	GDMS	GDMS	PIXIE	GDMS	GDMS
ppm	precision	Confidence Interval	Confidence Interval	Confidence Interval	Confidence Interval	5 ppm OEM Limit	5 ppm OEM Limit
	sample type	Cu Chop	Copper	Copper	Copper	Copper	Copper
	ingot	n/a	14-00-01	14-00-01	14-00-01	14-00-01A	14-00-01R
	workup	A	Patent	Patent	Patent	Patent	Patent
No.		Average	Max	Max	Max	Max	Max
1	H	99.9999					
2	He						
3	Li						
4	Be						
5	B	0.0010	#DIV/0!				
6	C					63.25	56.12
7	N						
8	O				235250	128880	1683
9	F					3290	1534
10	Ne					634.3	3142
11	Na						678.9
12	Mg	0.0040	0.0125				
13	Al	0.3936	2.3019	1350	959.198	1910	208.6
14	Si	0.0760	0.1689	6530	5640	6320	50.15
15	P	0.0130	0.0485				314
16	S	3.6600	8.3912	24	24		251.7
17	Cl	0.1260	0.2146				241.4
18	Ar			112	162	350.719	212.406
19	K	0.0300	#DIV/0!				
20	Ca						20.75
21	Sc						24.22
22	Ti	0.0114	0.0302		53		
23	V						
24	Cr	0.0340	0.1657				
25	Mn	0.0136	0.0391				
26	Fe	2.1520	4.8122	53		472.395	461.03
27	Co	0.0140	0.0342				62.38
28	Ni	0.5520	1.0635				73.99
29	Cu	Matrix	Matrix	991100	990300	781580	862230
30	Zn						995600
31	Ge						993900
32	Ge						995500
33	As	0.4760	0.8351				996100
34	Se	0.6160	0.9602				993500
35	Br						995900
36	Kr						
37	Rb						
38	Sr						
39	Y						
40	Zr						
41	Nb						
42	Mo	0.0153	0.0390				
43	Tc						
44	Ru						
45	Rh			372	315		
46	Pd						
47	Ag	8.7800	10.2431				42.7
48	Cd						43.75
49	In	Blender					40.91
50	Sn	0.2900	0.7513				42.83
51	Sb	0.4960	1.1273				43.48
52	Te	0.1340	0.3199				42.11
53	I						
54	Xe						
55	Cs						
56	Ba	0.0035	0.0090				
57	La						
58	Ce			106			
59	Pr						
60	Nd						
61	Pm						
62	Sm						
63	Eu						
64	Gd						
65	Tb						
66	Dy						
67	Ho						
68	Er						
69	Tm						
70	Yb			149			
71	Lu						
72	Hf						
73	Ta						
74	W	0.2183	1.1874				
75	Re			126	155		
76	Os						
77	Ir			118	78		
78	Pt						
79	Au						
80	Hg						
81	Tl						
82	Pb	0.7620	1.8283				91.65
83	Bi	0.1760	0.2922				83.3
84	Po						95.1
85	At						109.3
86	Rn						104
87	Fr						109.3
88	Ra						
89	Ac						
90	Th						
91	Pa						
92	U						
				99.00%	100.20%	78.475	87.114
							200.00
							N/A
							110.30
							0.2

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